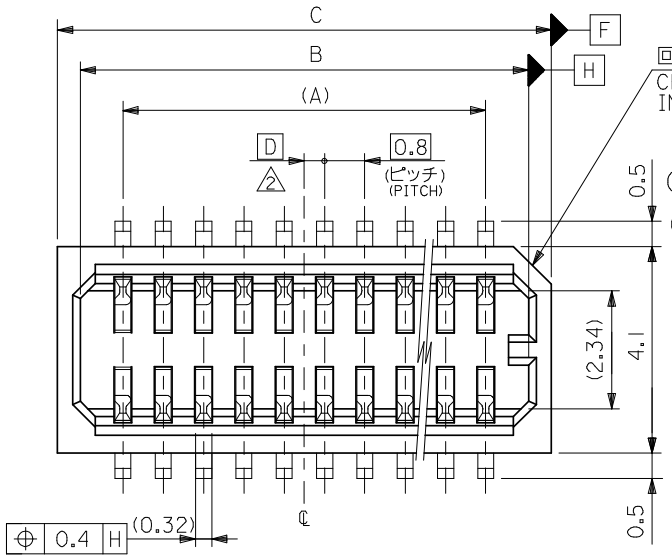
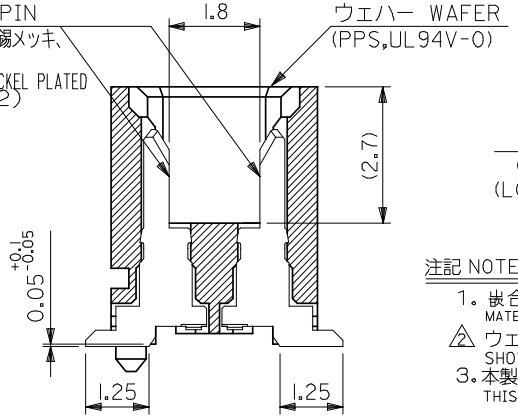
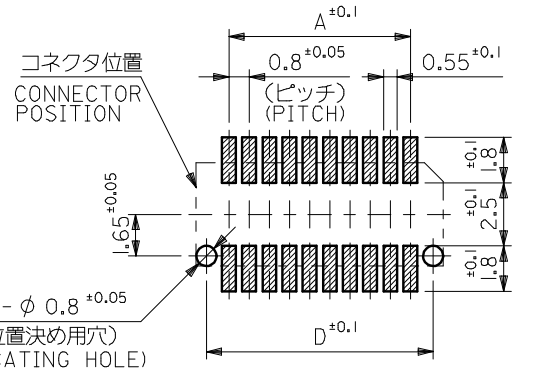


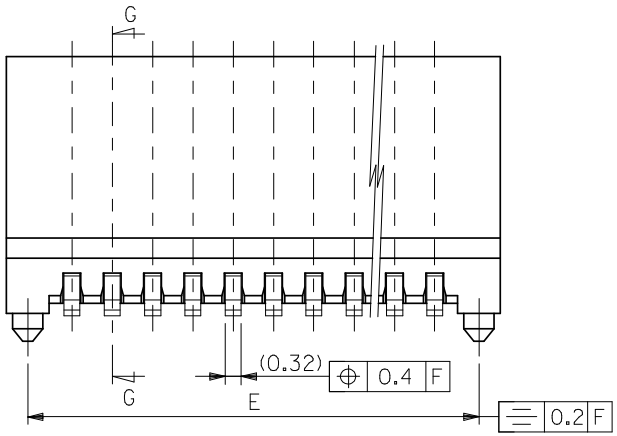


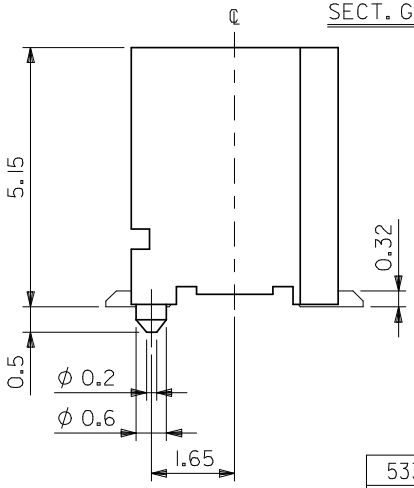


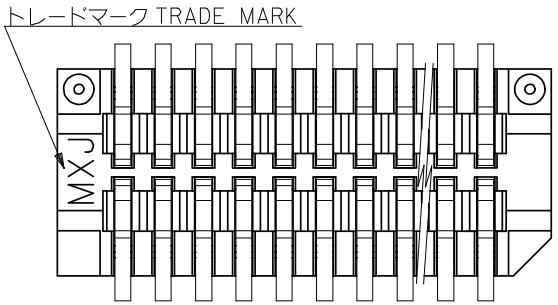
参考基板レイアウト(マウント面)
P.C.B. PATTERN LAYOUT (REF.) (MOUNT AREA)

注記 NOTES

1. 嵌合相手:52465 シリーズ
MATES WITH : 52465 SERIES
2. ウェハーの ℄ から隣接するピンの ℄ 迄の位置を示す。
SHOW POSITION FROM ℄ OF WAFER TO ℄ OF ADJACENT PINS.
3. 本製品は 53364-**17 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53364-**17







	17.0	0.4	17.8	16.9	15.2	53364-4019	40
	15.4	0.4	16.2	15.3	13.6	53364-3619	36
	13.0	0.8	13.8	12.9	11.2	53364-3019	30
	12.2	0.4	13.0	12.1	10.4	53364-2819	28
	9.0	0.4	9.8	8.9	7.2	53364-2019	20
	8.2	0.8	9.0	8.1	6.4	53364-1819	18
	5.8	0.4	6.6	5.7	4.0	53364-1219	12
53364-**19	5.0	0.8	5.8	4.9	3.2	53364-1019	10
MODEL NO.	E	D	C	B	A	MATERIAL NO.	極数CKT.

REVISED
EC NO: J2008-3931 2008/05/26
DRWN:NAKAMURAA 2008/05/26
CH'KD:T. HARUYAMA 2008/08/21
APPR:NUKITA
DESCRIPTION
A
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: M.NABEI DATE:
CHECKED BY: K.TOJO DATE:
APPROVED BY: M.SASAO DATE:
MATERIAL NO.: SEE TABLE

TITLE: 0.8 BOARD TO BOARD CONN. WAFER ASS ST.SMT -LEAD FREE-

molex MOLEX INCORPORATED

DOCUMENT NO.: SD-53364-001
SHEET NO.: 1 OF 1

SIZE A3

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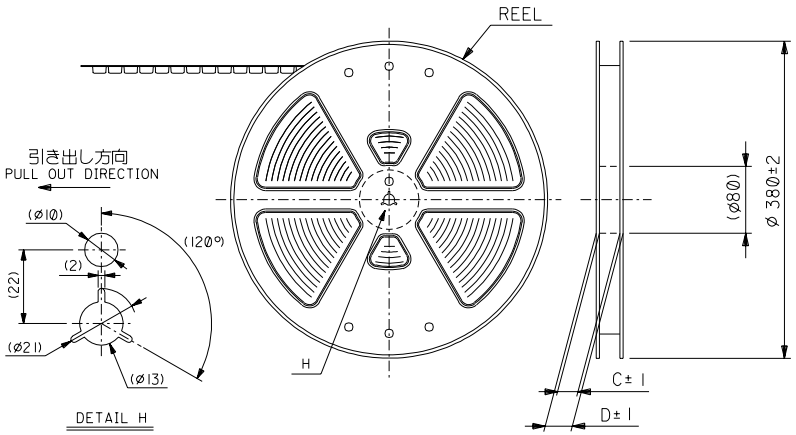
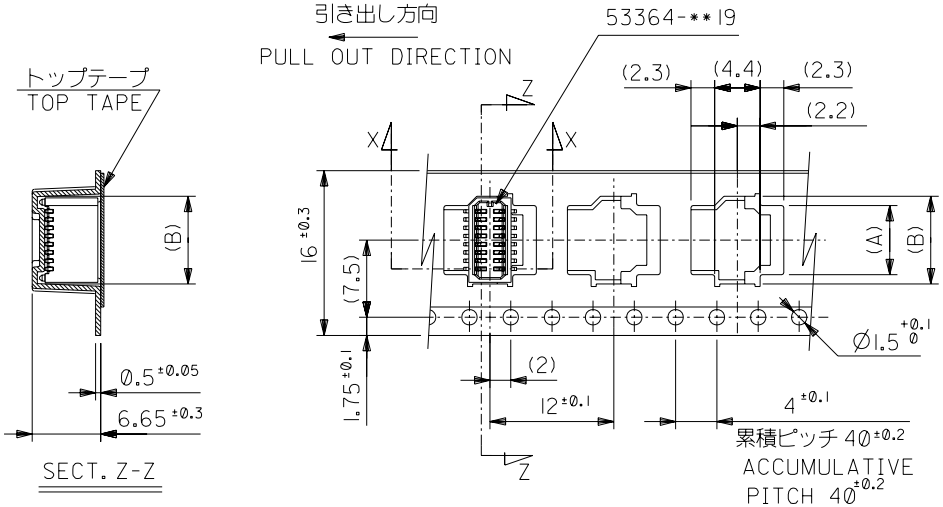


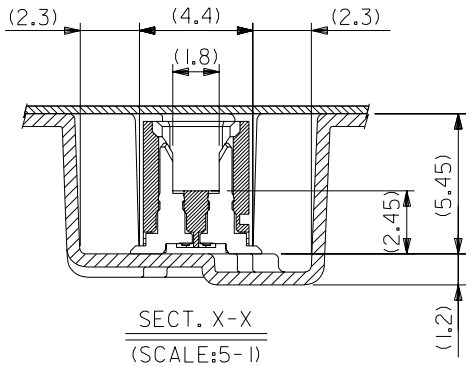
DETAIL H



SECT. Z-Z

16mm幅キャリアテープ

16mm WIDTH CARRIER TAPE



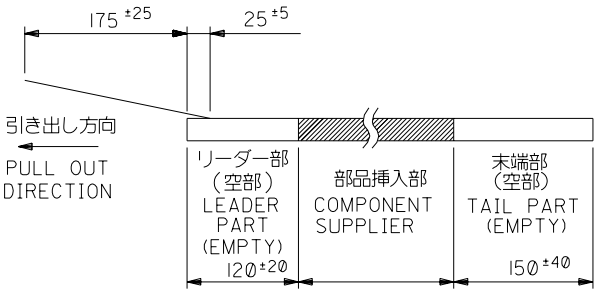
SECT. X-X

(SCALE:5-1)

注記 NOTES

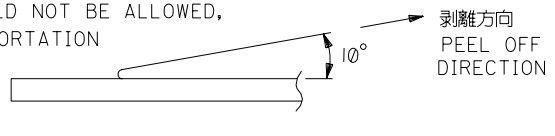
1. 梱包数量：1000個／リール NUMBER OF CONNECTORS:1000PCS/REEL

2. リードテープ長さ LEAD TAPE LENGTH



3. トップテープの剥離強度：（剥離方向は下図参照）
0.1～1.3N {10 ～ 130gf} 尚、本規格値は、出荷時に適用。
（但し、輸送時に剥離が発生しない事。）

PEELING OFF FORCE OF TOP TAPE
0.1～1.3N {10 ～130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLITED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



4. 材料 MATERIAL
キャリアテープ：ポリプロピレン（PP） CARRIER TAPE:POLYPROPYLENE
トップテープ：PET，PE，PEF TOP TAPE:PET,PE,PEF
リール：ポリスチレン（PS） REEL:POLYSTYRENE(PS)
<リサイクル材を含む> <RECYCLE MATERIAL CONTAINED>

5. 本製品は 53364-**90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53364-**90

MODEL NO.	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
53364-**70	16	21.4	17.4	9.3	7.5	53364-1870	18
				6.9	5.1	53364-1270	12
				6.1	4.3	53364-1070	10

角度 ANGLE	±3°
30 以上 OVER 未満 UNDER	±0.3
10 以上 OVER 30 UNDER	±0.25
未満 10 UNDER	±0.2

一般公差 GENERAL TOLERANCES

記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
0	新規作成 RELEASED (J2004-2958)	M.N M.S	'04/03/09

材料 MATERIAL 注記参照 SEE NOTES
仕上げ FINISH —#—
適用電線範囲 WIRE RANGE —#—
被覆外径 INS. RANGE —#—
DRAWN BY '04/03/09 M.NABEI
CHK'D BY '04/03/09 K.TOJO
APP'D BY '03/04/09 M.SASAO
尺度 SCALE —#—

MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
0.8 BtB Conn Wafer Assy
ST SMT With Boss
Embstp Pkg -LEAD FREE-

DWG. NO. SD-53364-002 (SHEET 1 OF 2) REV 0

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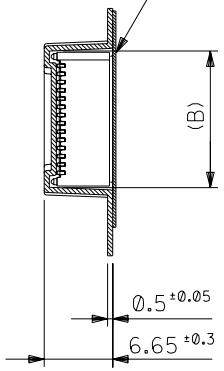
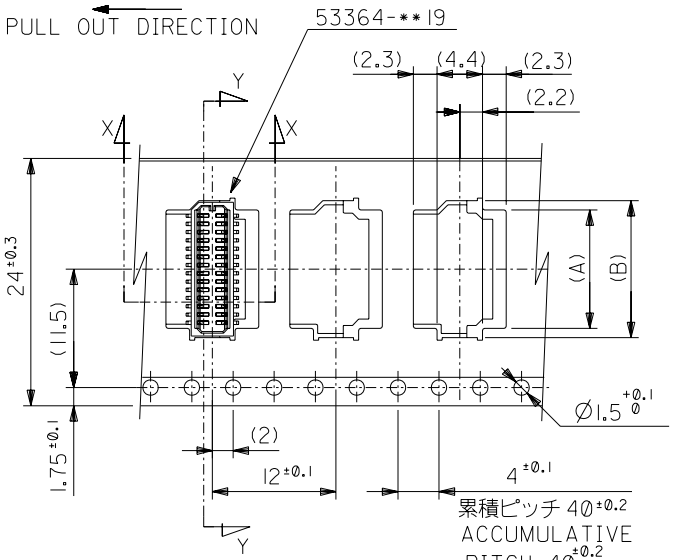
:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

DWG. NO. SD-53364-002

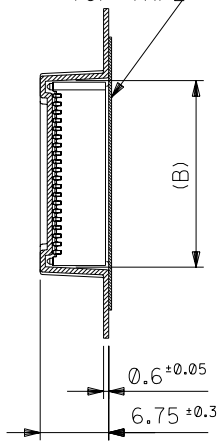
引き出し方向
PULL OUT DIRECTION



SECT. Y-Y

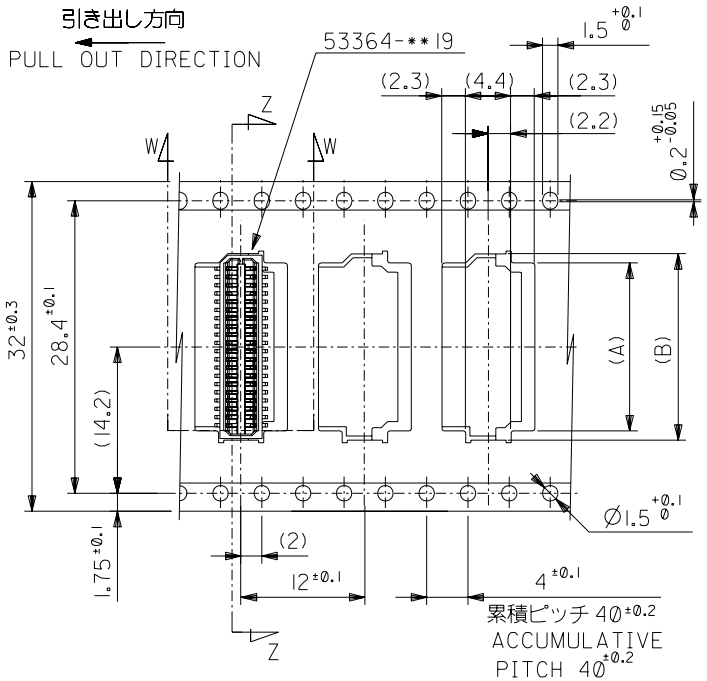


24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

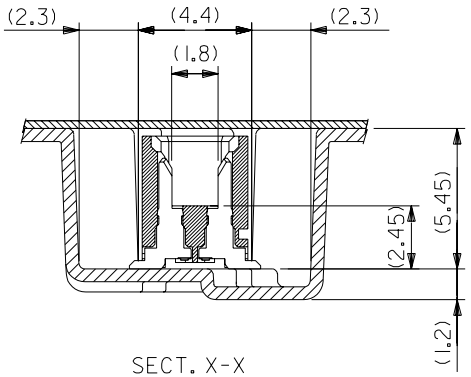


SECT. Z-Z

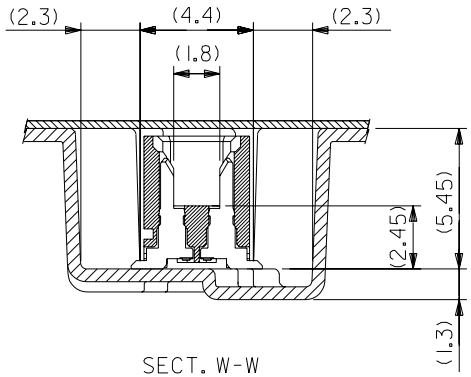
引き出し方向
PULL OUT DIRECTION



32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE



SECT. X-X
(SCALE:5-1)



SECT. W-W
(SCALE:5-1)

キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
32	37.4	33.4	18.1	16.3	53364-4070	40
24	29.4	25.4	16.5	14.7	53364-3670	36
			14.1	12.3	53364-3070	30
			13.3	11.5	53364-2870	28
			10.1	8.3	53364-2070	20

53364-**70
MODEL NO.

角度 ANGLE	±3°
30以上 OVER	±0.3
10以上 OVER 30未満 UNDER	±0.25
10未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
0	新規作成 RELEASED (J2004-2958)	M.N M.S	'04/03/09

材料 MATERIAL
SHEET 1 OF 2 参照
REFER TO SHEET 1 OF 2

仕上げ FINISH —#—

適用電線範囲 WIRE RANGE —#—

被覆外径 INS. RANGE —#—

DRAWN BY '04/03/09	CHK'D BY '04/03/09
M.NABEI	K.TOJO
APP'D BY '04/03/09	尺度 SCALE
M.SASAO	—#—

MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
0.8 BtB Conn Wafer Assy
ST SMT With Boss
Embstp Pkg -LEAD FREE-

DWG. NO. (SHEET 2 OF 2) SD-53364-002

REV 0

:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

SD-53364-002.S02

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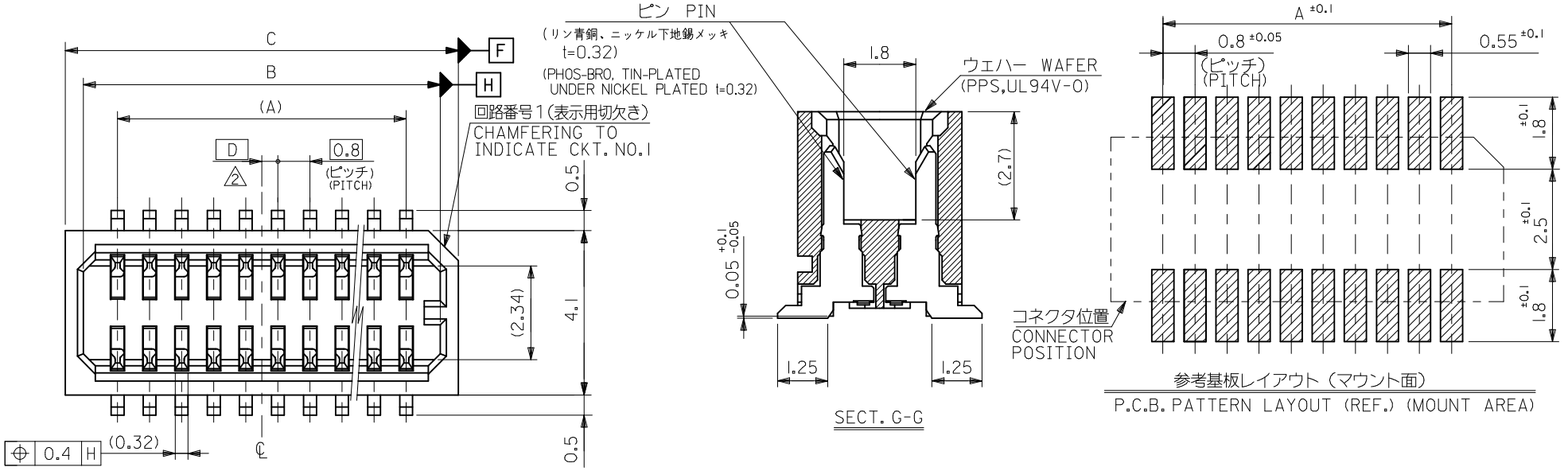
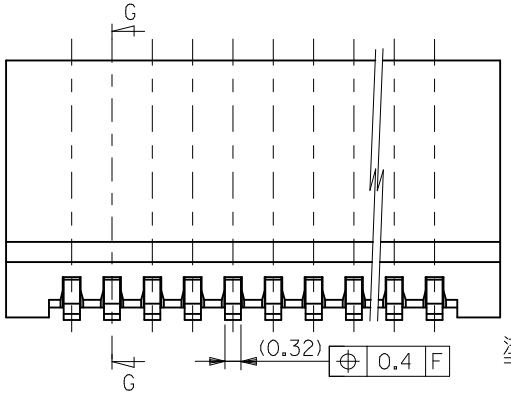
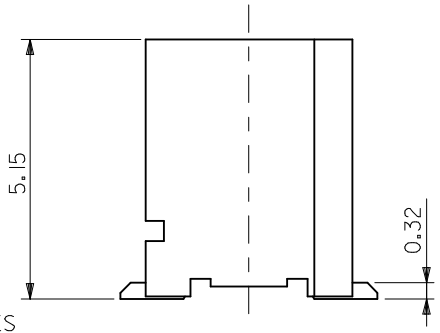
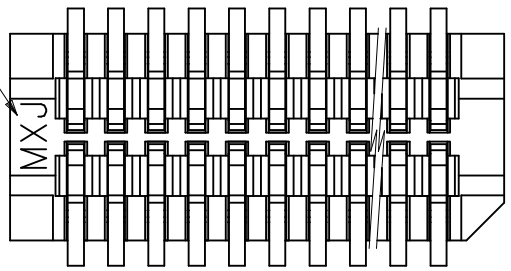
EN-0IC(032)MXJ-32







トレードマーク TRADE MARK



注記 NOTES

1. 嵌合相手:52465,52588シリーズ
MATES WITH : 52465,52588 SERIES

2. ウェハーの ℄ から隣接するピンの ℄ 迄の位置を示す。
SHOW POSITION FROM ℄ OF WAFER TO ℄ OF ADJACENT PINS.

3. 本製品は53364-**27の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53364-**27.

D	C	B	A	MATERIAL NO.	極数 CKT.
0.4	16.2	15.3	13.6	53364-3629	36
0.8	13.8	12.9	11.2	53364-3029	30
0.4	9.8	8.9	7.2	53364-2029	20
0.8	9.0	8.1	6.4	53364-1829	18

REVISED
EC NO: J2016-1237
DRWN:MNISHIKAWA 2016/06/07
CH'KD:YOITO 2016/06/07
APPR:YOITO 2016/06/16
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

0.25	UNDER	UNDER	±0.2
0.25	OVER 0.5	UNDER	±0.2
0.5	OVER 1.0	UNDER	±0.2
1.0	OVER 10	UNDER	±---
10	OVER 30	UNDER	±---
30	OVER		±---
ANGULAR	±1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 10:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: M.NABEI DATE: '04/03/09
CHECKED BY: K.TOJO DATE: '04/03/09
APPROVED BY: M.SASAO DATE: '04/03/09
MATERIAL NO.: SEE CHART

TITLE: 0.8 BOARD TO BOARD CONN. WAFFER ASSY ST.SMT -LEAD FREE-

molex

DOCUMENT NO.: SD-53364-003
SHEET NO.: 1 OF 2
SIZE: A3

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